Q1 (a) BOOKWORK

The conductivity at OK would be expected to be zero. All the electrons would be in bonds and there would be no themal energy to allow them to escape. As the temperature is raised thermal energy wincreases and some electrons will escape and be free to move around the material, bleaving behind a hole in a bonding state which is the charged and also free to move. Both these particles will be able to conduct electricity and so the conductivity rises.

(b) BOOKWORK, all info on examination sheet.

$$\delta = nq \mu_e + pq \mu_h$$

$$n = p = n_i = 1.45 \times 10^{16} \text{ m}^3, \quad \mu_e = 0.07 \text{ m}^2 \text{ Vs}^{-1}, \quad \mu_h = 0.045 \text{ m}^2 \text{ V}^{-1} \text{ s}^{-1}$$

$$\delta = 1.63 \times 10^{-14} + 1.05 \times 10^{-14}$$

$$\delta = 2.68 \times 10^{-14} \cdot \Omega^{-1} \text{ m}^{-1}$$
[3]

(c) APPLIED BOOKWOVEK

The total conductivity

$$P = 10^{21} \text{ m}^{-3}$$

$$N_p = \frac{n_i^2}{p} = 2 \cdot 1 \times 10^{11} \text{ m}^3$$

$$\delta = \delta_n + \delta_p \Rightarrow \delta_n = 2 \cdot 36 \times 10^{-9}$$

$$\delta_p = 7 \cdot 2 \times 10^{\circ}$$

$$\delta_n \ll \delta_p \approx \delta_r = 7 \cdot 2 \times 10^{\circ}$$
Fractional contribution from holes a form = $\frac{\delta_p}{\delta_n + \delta_p} \approx \frac{2}{\delta_p}$
Fractional contribution from electrons = $\frac{\delta_n}{\delta_n + \delta_p} \approx \frac{2}{\delta_p} = 3 \cdot 3 \times 10^{-10}$

(d) Hidden

$$\frac{G'}{G} = \frac{n'p'}{n_i^2} \in$$

$$n' = p'$$

$$\frac{G'}{G} = \frac{n^2}{n_u^2}$$

$$10^{6} = \frac{n^{2}}{n_{i}^{2}}$$

$$-10^3 n_i$$

The reason for the increase is due to absorption of light creating electron-hole pairs as photons provide the energy for as electrons to escape from its bonds

(2)

C1

 C_{1}



Under forward him we first need to know the number of

As junction

BOOKWORK, although proof in notes does not assume Iho>> Ieo which can be made here, simplifying the proof.

As pt-n we can assume Iho>> Ieo and therefore need only consider the hole current.

Under forward bias, the excess holes injected across the junction Spo can be given by Spo = Pno - Pn

Por P(P) = Pno exp(2(Vo-V))

$$\delta_{PO} = \frac{P_{(p)}}{P_{no} \exp \frac{2(v_0 - v)}{kT}} - \frac{P_{(p)}}{P_n \exp \left(\frac{2v_0}{kT}\right)}$$

. . Substituting again for P(p)

Now the the total charge existing in the n-type material Qp will be given by Qp = qA / Sp(x) doc

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where
$$\delta_{p,(\infty)} = \delta_{p_0} \exp\left(\frac{2\zeta_{h}}{L_h}\right)$$

This charge 8 exists for the

On average the charges exist for Th

and hence

(b) APPLIED BOOKWORK, recifiers not explicitly explained in course.

In a rectifier an ac. signal is applied across the click. In for half the cycle the diode will be reverse biased, so no current will flow, apart from a small leahage current as the built in potential carross the junction will be larger. In the other half of the cycle the diode it forward biased and the built in potential will be eventually overcopie with electrons and holes being injected across the junction and recombining allowing a significant current to flow. Here

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$$10''(+1) = exp \left[\frac{1.60 \times 10^{19}}{10.38 \times 10^{23} \times 300} \right]$$

Vd = Voltage drop across diode.

There are two diodes for each half of the agele

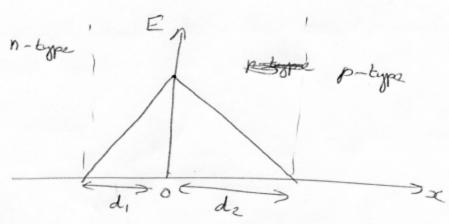
3 (a) BOOKWORK

$$\frac{dE}{dx} = \frac{1}{2} = \frac{Nd9}{E} = \frac{Na9}{E}$$

$$\frac{1}{2000} = \frac{1}{200}$$









$$E(0c) = \int \frac{Nd2}{E} dx = \frac{Nd2x}{E} + C$$

$$C_{1}$$

Similarly for 050c5dz

Let Brown Nd >> Na and i. d. «d2 Vo = 9 Nd do 1 d= /2EEFVo

b) Applied bookwork

for b-e junction Forward biassed and n-p

As Vbe = Vo d = 0.

For c-b junction reverse biased and
$$p^{+}-n$$

$$d = \sqrt{\frac{2 \varepsilon_{o} \varepsilon_{r}}{9} N_{d}}$$

(C) More difficult applied prostudents have to apply known equation

$$\frac{dp}{dn} = \frac{N_d}{N_a}$$

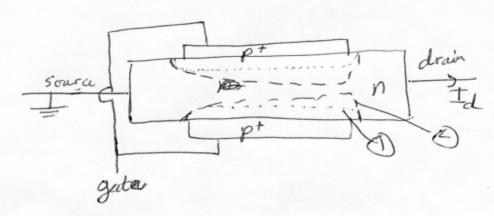
From above dn = 3.6×107 m

[z]

(d) As the increases the base region thickness will effectively decrease slightly as the depletin region around the C-B junction increases. This reduction in the base thickness should cause the transister gain to increase slightly [4]

4 (a) BOOKWORK

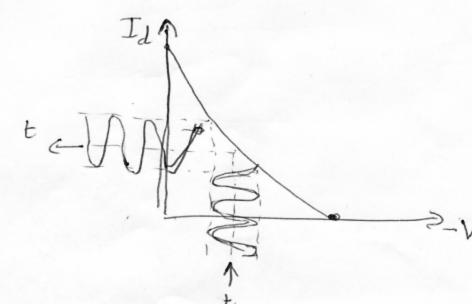
The pysical structure should be shown as below, with a single channel device on an insultrating substrate



Under low Vds current will flow through the n-channel with some small voltage drop lue to the resistance of the channel. As Vds increases the gate-drain voltage will become more reverse biased and whence the depletien region will grow from the dotted line 1 to the dashed line 2 hence the channel is constricted and the resistance increase. Eventually the Bitution is reached whereby the constriction is such that Id remains constance for exerincreasing Vds. If a reverse biased gate Voltage is applied the channel is narrower to start with and the point where Id becomes constant is lower. This gives a family of curves below Id increasing reverse bias on gate,

(b) More advanced booknork. B

In the IFET we wish to characterise the change in output drain current, against the change in input gate voltage. The transfer characteristic is a plot of this function:



It shows how the input voltage on the gate can stransfer to the output current in the amplifier region.

The transconducture is the slope of this line at the quiescent point, given by 1 2 Td / gm = 2 Vg / Vg



At the Quiesunt point Id = Voltage drop across R. 755-7.5V

> = 5mA [4]

Ld (pk-pk) = gm Vgs (pk-pk) = 0.12 × 0.01 = 1.2 mA

(S)

It id variest between 4.4 and 5.6 mA

(1)

.. Vdrap across PSK, varies between 6.6 and 8.4V

: Vout = 1.8 V (peak-peak)

[1]

Vgain = Vorit = 1.8 = 180

